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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	ARM920T
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	200MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	LCD
Ethernet	-
SATA	-
USB	USB 1.x (1)
Voltage - I/O	1.8V, 3.0V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	256-LFBGA
Supplier Device Package	256-PBGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9328mxlvm20

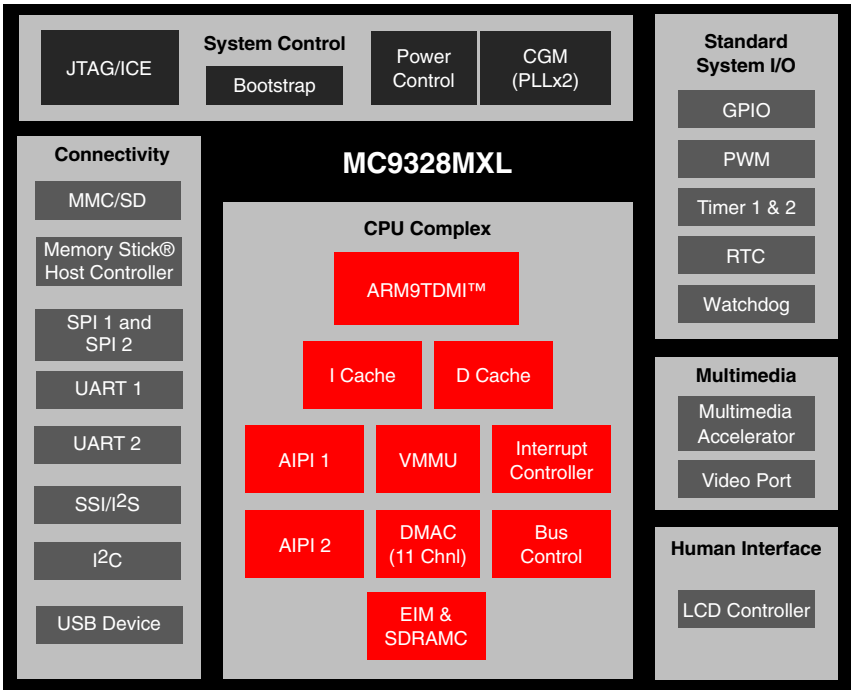


Figure 1. i.MXL Functional Block Diagram

1.1 Features

To support a wide variety of applications, the processor offers a robust array of features, including the following:

- ARM920T™ Microprocessor Core
- AHB to IP Bus Interfaces (AIPIs)
- External Interface Module (EIM)
- SDRAM Controller (SDRAMC)
- DPLL Clock and Power Control Module
- Two Universal Asynchronous Receiver/Transmitters (UART 1 and UART 2)
- Serial Peripheral Interface (SPI)
- Two General-Purpose 32-bit Counters/Timers
- Watchdog Timer
- Real-Time Clock/Sampling Timer (RTC)
- LCD Controller (LCDC)
- Pulse-Width Modulation (PWM) Module
- Universal Serial Bus (USB) Device
- Multimedia Card and Secure Digital (MMC/SD) Host Controller Module
- Memory Stick® Host Controller (MSHC)
- Direct Memory Access Controller (DMAC)
- Synchronous Serial Interface and an Inter-IC Sound (SSI/I^2S) Module
- Inter-IC (I^2C) Bus Module

Table 2. i.MXL Signal Descriptions (Continued)

Signal Name	Function/Notes
Bootstrap	
BOOT [3:0]	System Boot Mode Select—The operational system boot mode of the i.MXL processor upon system reset is determined by the settings of these pins.
SDRAM Controller	
SDBA [4:0]	SDRAM non-interleave mode bank address multiplexed with address signals A [15:11]. These signals are logically equivalent to core address p_addr [25:21] in SDRAM cycles.
SDIBA [3:0]	SDRAM interleave addressing mode bank address multiplexed with address signals A [19:16]. These signals are logically equivalent to core address p_addr [12:9] in SDRAM cycles.
MA [11:10]	SDRAM address signals
MA [9:0]	SDRAM address signals which are multiplexed with address signals A [10:1]. MA [9:0] are selected on SDRAM cycles.
DQM [3:0]	SDRAM data enable
$\overline{\text{CSD0}}$	SDRAM Chip-select signal which is multiplexed with the $\overline{\text{CS2}}$ signal. These two signals are selectable by programming the system control register.
$\overline{\text{CSD1}}$	SDRAM Chip-select signal which is multiplexed with $\overline{\text{CS3}}$ signal. These two signals are selectable by programming the system control register. By default, $\overline{\text{CSD1}}$ is selected, so it can be used as boot chip-select by properly configuring BOOT [3:0] input pins.
$\overline{\text{RAS}}$	SDRAM Row Address Select signal
$\overline{\text{CAS}}$	SDRAM Column Address Select signal
$\overline{\text{SDWE}}$	SDRAM Write Enable signal
SDCKE0	SDRAM Clock Enable 0
SDCKE1	SDRAM Clock Enable 1
SDCLK	SDRAM Clock
$\overline{\text{RESET\_SF}}$	Not Used
Clocks and Resets	
EXTAL16M	Crystal input (4 MHz to 16 MHz), or a 16 MHz oscillator input when the internal oscillator circuit is shut down.
XTAL16M	Crystal output
EXTAL32K	32 kHz crystal input
XTAL32K	32 kHz crystal output
CLKO	Clock Out signal selected from internal clock signals.
$\overline{\text{RESET\_IN}}$	Master Reset—External active low Schmitt trigger input signal. When this signal goes active, all modules (except the reset module and the clock control module) are reset.
$\overline{\text{RESET\_OUT}}$	Reset Out—Internal active low output signal from the Watchdog Timer module and is asserted from the following sources: Power-on reset, External reset ($\overline{\text{RESET\_IN}}$), and Watchdog time-out.
POR	Power On Reset—Internal active high Schmitt trigger input signal. The POR signal is normally generated by an external RC circuit designed to detect a power-up event.

Table 2. i.MXL Signal Descriptions (Continued)

Signal Name	Function/Notes
JTAG	
$\overline{\text{TRST}}$	Test Reset Pin—External active low signal used to asynchronously initialize the JTAG controller.
$\overline{\text{TDO}}$	Serial Output for test instructions and data. Changes on the falling edge of TCK.
TDI	Serial Input for test instructions and data. Sampled on the rising edge of TCK.
TCK	Test Clock to synchronize test logic and control register access through the JTAG port.
TMS	Test Mode Select to sequence the JTAG test controller's state machine. Sampled on the rising edge of TCK.
DMA	
$\overline{\text{DMA\_REQ}}$	$\overline{\text{DMA Request}}$—external DMA request signal. Multiplexed with SPI1_SPI_RDY.
BIG_ENDIAN	Big Endian—Input signal that determines the configuration of the external chip-select space. If it is driven logic-high at reset, the external chip-select space will be configured to big endian. If it is driven logic-low at reset, the external chip-select space will be configured to little endian. This input must not change state after power-on reset negates or during chip operation.
ETM	
ETMTRACESYNC	ETM sync signal which is multiplexed with A24. ETMTRACESYNC is selected in ETM mode.
ETMTRACECLK	ETM clock signal which is multiplexed with A23. ETMTRACECLK is selected in ETM mode.
ETMPIPESTAT [2:0]	ETM status signals which are multiplexed with A [22:20]. ETMPIPESTAT [2:0] are selected in ETM mode.
ETMTRACEPKT [7:0]	ETM packet signals which are multiplexed with $\overline{\text{ECB}}$, $\overline{\text{LBA}}$, BCLK (burst clock), PA17, A [19:16]. ETMTRACEPKT [7:0] are selected in ETM mode.
CMOS Sensor Interface	
CSI_D [7:0]	Sensor port data
CSI_MCLK	Sensor port master clock
CSI_VSYNC	Sensor port vertical sync
CSI_HSYNC	Sensor port horizontal sync
CSI_PIXCLK	Sensor port data latch clock
LCD Controller	
LD [15:0]	LCD Data Bus—All LCD signals are driven low after reset and when LCD is off.
FLM/VSYNC	Frame Sync or Vsync—This signal also serves as the clock signal output for the gate driver (dedicated signal SPS for Sharp panel HR-TFT).
LP/HSYNC	Line pulse or H sync
LSCLK	Shift clock
ACD/OE	Alternate crystal direction/output enable.
CONTRAST	This signal is used to control the LCD bias voltage as contrast control.
SPL_SPR	Program horizontal scan direction (Sharp panel dedicated signal).
PS	Control signal output for source driver (Sharp panel dedicated signal).

Table 3. MC9328MXLMC9328MXS Signal Multiplexing Scheme (Continued)

I/O Supply Voltage	225 BGA Ball	256 BGA Ball	Primary			Alternate		GPIO		AIN	BIN	AOUT	Default
			Signal	Dir	Pull-Up	Signal	Dir	Mux	Pull-Up				
NVDD1	N11	T9	DQM2	O									
NVDD1	P11	N9	DQM1	O									
NVDD1	N12	R10	DQM0	O									
NVDD1	P12	M9	$\overline{RAS}$	O									
NVDD1	R13	L8	$\overline{CAS}$	O									
NVDD1	R14	T10	$\overline{SDWE}$	O									
NVDD1	N13	R11	SDCKE0	O									
NVDD1	P13	P10	SDCKE1	O									
NVDD1	P15	N10	$\overline{RESET\_SF}$	O									
NVDD1	P14	T11	CLKO	O									
AVDD1	R15	T12	AVDD1	Static									
QVDD2	M13	R15	QVDD2	Static									
AVDD1	N15	P13	$\overline{TRST}$	I	69K								
AVDD1	N14	T13	TRISTATE[1]	I									
AVDD1	M15	T14	EXTAL16M	I									
AVDD1	L14	T15	XTAL16M	O									
AVDD1	L15	R16	EXTAL32K	I									
AVDD1	K15	P16	XTAL32K	O									
AVDD1	M14	M10	$\overline{RESET\_IN}$[2]	I	69K								
AVDD1	K14	N11	$\overline{RESET\_OUT}$	O									
AVDD1	L12	R12	POR[2]	I									
AVDD1	K13	M11	BIG_ENDIAN[3]	I									
AVDD1	M12	P11	BOOT3[3]	I									
AVDD1	K11	N12	BOOT2[3]	I									
AVDD1	J14	R13	BOOT1[3]	I									
AVDD1	J15	P12	BOOT0[3]	I									
NVDD2	J13	R14	$\overline{TDO}$[4]	O									
NVDD2	H15	N15	TMS	I	69K								
NVDD2	J12	L9	TCK	I	69K								
NVDD2	K12	N16	TDI	I	69K								
NVDD2	J11	P14	I2C_SCL	O				PA16	69K				PA16
NVDD2	H14	P15	I2C_SDA	I/O				PA15	69K				PA15

Table 3. MC9328MXLMC9328MXS Signal Multiplexing Scheme (Continued)

I/O Supply Voltage	225 BGA Ball	256 BGA Ball	Primary			Alternate		GPIO		AIN	BIN	AOUT	Default
			Signal	Dir	Pull-Up	Signal	Dir	Mux	Pull-Up				
NVDD2	H13	N13	CSI_PIXCLK	I				PA14	69K				PA14
NVDD2	G14	M13	CSI_HSYNC	I				PA13	69K				PA13
NVDD2	H12	M14	CSI_VSYNC	I				PA12	69K				PA12
NVDD2	G13	N14	CSI_D7	I				PA11	69K				PA11
NVDD2	J10	M15	CSI_D6	I				PA10	69K				PA10
NVDD2	G15	M16	CSI_D5	I				PA9	69K				PA9
NVDD2	F15	M12	CSI_D4	I				PA8	69K				PA8
NVDD2	G12	L16	CSI_D3	I				PA7	69K				PA7
NVDD2	F14	L15	CSI_D2	I				PA6	69K				PA6
NVDD2	H11	L14	CSI_D1	I				PA5	69K				PA5
NVDD2	E14	L13	CSI_D0	I				PA4	69K				PA4
NVDD2	E15	L12	CSI_MCLK	O				PA3	69K				PA3
NVDD2	G11	L11	PWMO	O				PA2	69K				PA2
NVDD2	E13	L10	TIN	I				PA1	69K			SPI2_RXD_0	PA1
NVDD2	D14	K15	TMR2OUT	O				PD31	69K		SPI2_TXD		PD31
NVDD2	F13	K16	LD15	O				PD30	69K				PD30
NVDD2	F12	K14	LD14	O				PD29	69K				PD29
NVDD2	D15	K13	LD13	O				PD28	69K				PD28
NVDD2	C14	K12	LD12	O				PD27	69K				PD27
NVDD2	D13	J14	LD11	O				PD26	69K				PD26
NVDD2	E12	K11	LD10	O				PD25	69K				PD25
NVDD2	C13	H15	LD9	O				PD24	69K				PD24
NVDD2	C12	J13	LD8	O				PD23	69K				PD23
NVDD2	B15	J12	LD7	O				PD22	69K				PD22
NVDD2	B14	J11	LD6	O				PD21	69K				PD21
NVDD2	A15	H14	LD5	O				PD20	69K				PD20
NVDD2	A14	H13	LD4	O				PD19	69K				PD19
NVDD2	B13	H16	LD3	O				PD18	69K				PD18
NVDD2	A13	H12	LD2	O				PD17	69K				PD17
NVDD2	D12	G16	LD1	O				PD16	69K				PD16
NVDD2	B12	H11	LD0	O				PD15	69K				PD15
NVDD2	C11	G15	FLM/VSYNC	O				PD14	69K				PD14

Table 3. MC9328MXLMC9328MXS Signal Multiplexing Scheme (Continued)

I/O Supply Voltage	225 BGA Ball	256 BGA Ball	Primary			Alternate		GPIO		AIN	BIN	AOUT	Default
			Signal	Dir	Pull-Up	Signal	Dir	Mux	Pull-Up				
NVDD4	D8	F7	UART2_TXD	O				PB30	69K				PB30
NVDD4	E7	E7	$\overline{\text{UART2\_RTS}}$	I				PB29	69K				PB29
NVDD4	F7	C6	$\overline{\text{UART2\_CTS}}$	O				PB28	69K				PB28
NVDD4	B6	D7	USBD_VMO	O				PB27	69K				PB27
NVDD4	C6	D6	USBD_VPO	O				PB26	69K				PB26
NVDD4	A6	E6	USBD_VM	I				PB25	69K				PB25
NVDD4	D6	B6	USBD_VP	I				PB24	69K				PB24
NVDD4	A5	D5	USBD_SUSPND	O				PB23	69K				PB23
NVDD4	B5	C5	USBD_RCV	I/O				PB22	69K				PB22
NVDD4	A4	B5	$\overline{\text{USBD\_ROE}}$	O				PB21	69K				PB21
NVDD4	B4	A5	USBD_AFE	O				PB20	69K				PB20
NVDD4	A3	G7	PB19	I/O					69K				PB19
NVDD4	C4	F6	PB18	I/O					69K				PB18
NVDD4	D4	G6	PB17	O					69K				PB17
NVDD4	B3	B4	PB16	I					69K				PB16
NVDD4	A2	C4	PB15	I					69K				PB15
NVDD4	C3	D4	PB14	I					69K				PB14
NVDD4	A1	B3	SD_CMD	I/O		MS_BS		PB13	69K				PB13
NVDD4	B2	A3	SD_CLK	O		MS_SCLKO		PB12	69K				PB12
NVDD4	B1	A2	SD_DAT3	I/O		MS_SDIO		PB11	69K (pull down)				PB11
NVDD4	C5	E5	SD_DAT2	I/O		MS_SCLKI		PB10	69K				PB10
NVDD4	D3	B2	SD_DAT1	I/O		MS_PI1		PB9	69K				PB9
NVDD4	C2	C3	SD_DAT0	I/O		MS_PI0		PB8	69K				PB8
NVDD1	D5	K8	NVDD1	Static									
	G6	A1	NVSS	Static									
NVDD1	E5	H5	NVDD1	Static									
	H6	T1	NVSS	Static									
QVDD1	J8	H9	QVDD1	Static									
	E6	H8	QVSS	Static									

Table 9. Trace Port Timing Diagram Parameter Table (Continued)

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
4a	Output hold time	2.28	–	2	–	ns
4b	Output setup time	3.42	–	3	–	ns

4.2 DPLL Timing Specifications

Parameters of the DPLL are given in Table 10. In this table, T_{ref} is a reference clock period after the pre-divider and T_{dck} is the output double clock period.

Table 10. DPLL Specifications

Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
DPLL input clock freq range	Vcc = 1.8V	5	–	100	MHz
Pre-divider output clock freq range	Vcc = 1.8V	5	–	30	MHz
DPLL output clock freq range	Vcc = 1.8V	80	–	220	MHz
Pre-divider factor (PD)	–	1	–	16	–
Total multiplication factor (MF)	Includes both integer and fractional parts	5	–	15	–
MF integer part	–	5	–	15	–
MF numerator	Should be less than the denominator	0	–	1022	–
MF denominator	–	1	–	1023	–
Pre-multiplier lock-in time	–	–	–	312.5	µsec
Freq lock-in time after full reset	FOL mode for non-integer MF (does not include pre-multi lock-in time)	250	280 (56 µs)	300	T_{ref}
Freq lock-in time after partial reset	FOL mode for non-integer MF (does not include pre-multi lock-in time)	220	250 (50 µs)	270	T_{ref}
Phase lock-in time after full reset	FPL mode and integer MF (does not include pre-multi lock-in time)	300	350 (70 µs)	400	T_{ref}
Phase lock-in time after partial reset	FPL mode and integer MF (does not include pre-multi lock-in time)	270	320 (64 µs)	370	T_{ref}
Freq jitter (p-p)	–	–	0.005 (0.01%)	0.01	$2 \bullet T_{dck}$
Phase jitter (p-p)	Integer MF, FPL mode, Vcc=1.8V	–	1.0 (10%)	1.5	ns
Power supply voltage	–	1.7	–	2.5	V
Power dissipation	FOL mode, integer MF, f_{dck} = 200 MHz, Vcc = 1.8V	–	–	4	mW

4.3 Reset Module

The timing relationships of the Reset module with the POR and RESET_IN are shown in Figure 3 and Figure 4.

NOTE

Be aware that NVDD must ramp up to at least 1.8V before QVDD is powered up to prevent forward biasing.

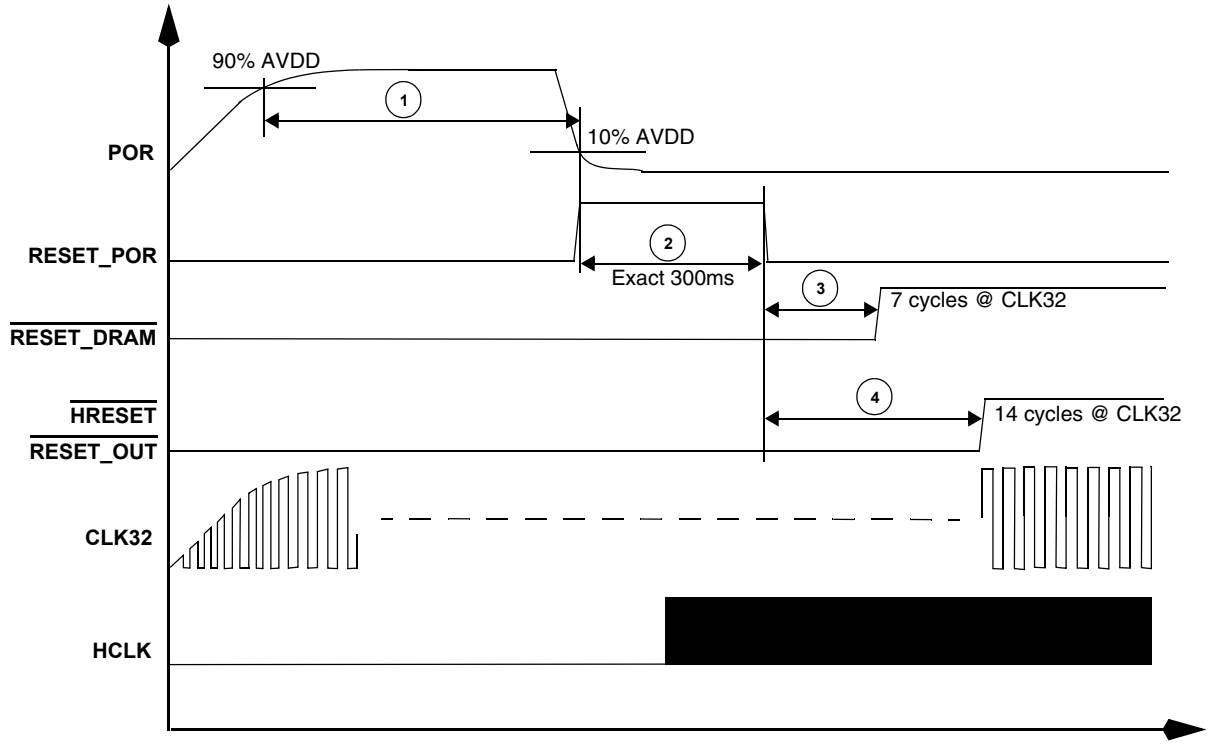


Figure 3. Timing Relationship with POR

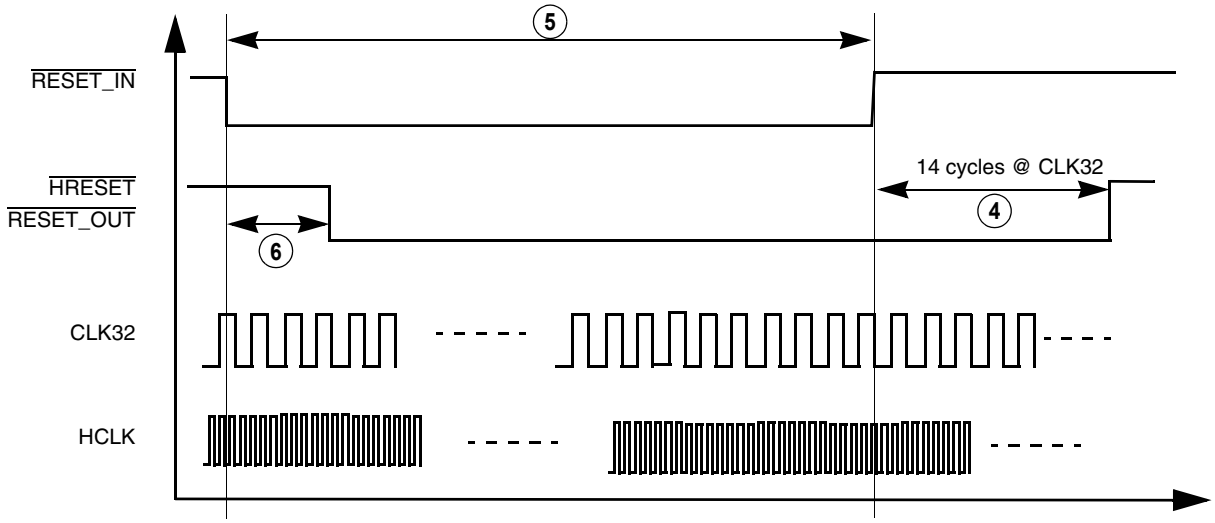


Figure 4. Timing Relationship with RESET_IN

Table 11. Reset Module Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Min	Max	Min	Max	
1	Width of input POWER_ON_RESET	note[1]	–	note[1]	–	–
2	Width of internal $\overline{\text{POWER\_ON\_RESET}}$ (CLK32 at 32 kHz)	300	300	300	300	ms
3	7K to 32K-cycle stretcher for SDRAM reset	7	7	7	7	Cycles of CLK32
4	14K to 32K-cycle stretcher for internal system reset $\overline{\text{HRESERT}}$ and output reset at pin $\overline{\text{RESET\_OUT}}$	14	14	14	14	Cycles of CLK32
5	Width of external hard-reset $\overline{\text{RESET\_IN}}$	4	–	4	–	Cycles of CLK32
6	4K to 32K-cycle qualifier	4	4	4	4	Cycles of CLK32

[1] POR width is dependent on the 32 or 32.768 kHz crystal oscillator start-up time. Design margin should allow for crystal tolerance, i.MX chip variations, temperature impact, and supply voltage influence. Through the process of supplying crystals for use with CMOS oscillators, crystal manufacturers have developed a working knowledge of start-up time of their crystals. Typically, start-up times range from 400 ms to 1.2 seconds for this type of crystal.
If an external stable clock source (already running) is used instead of a crystal, the width of POR should be ignored in calculating timing for the start-up process.

4.4 External Interface Module

The External Interface Module (EIM) handles the interface to devices external to the i.MXL processor, including the generation of chip-selects for external peripherals and memory. The timing diagram for the EIM is shown in Figure 5, and Table 12 defines the parameters of signals.

Table 14. DTACK WAIT Read Cycle DMA Enabled: WSC = 111111, DTACK_SEL=1, HCLK=96MHz (Continued)

Number	Characteristic	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
12	Wait pulse width	1T	1020T	ns

Note:
1. T is the system clock period. (For 96 MHz system clock, T=10.42 ns)
2. $\overline{OE}$ and $\overline{EB}$ assertion time is programmable by OEA bit in CS5L register. $\overline{EB}$ assertion in read cycle will occur only when EBC bit in CS5L register is clear.
3. Address becomes valid and $\overline{CS}$ asserts at the start of read access cycle.
4. The external wait input requirement is eliminated when $\overline{CS5}$ is programmed to use internal wait state.

4.4.2.3 WAIT Write Cycle without DMA

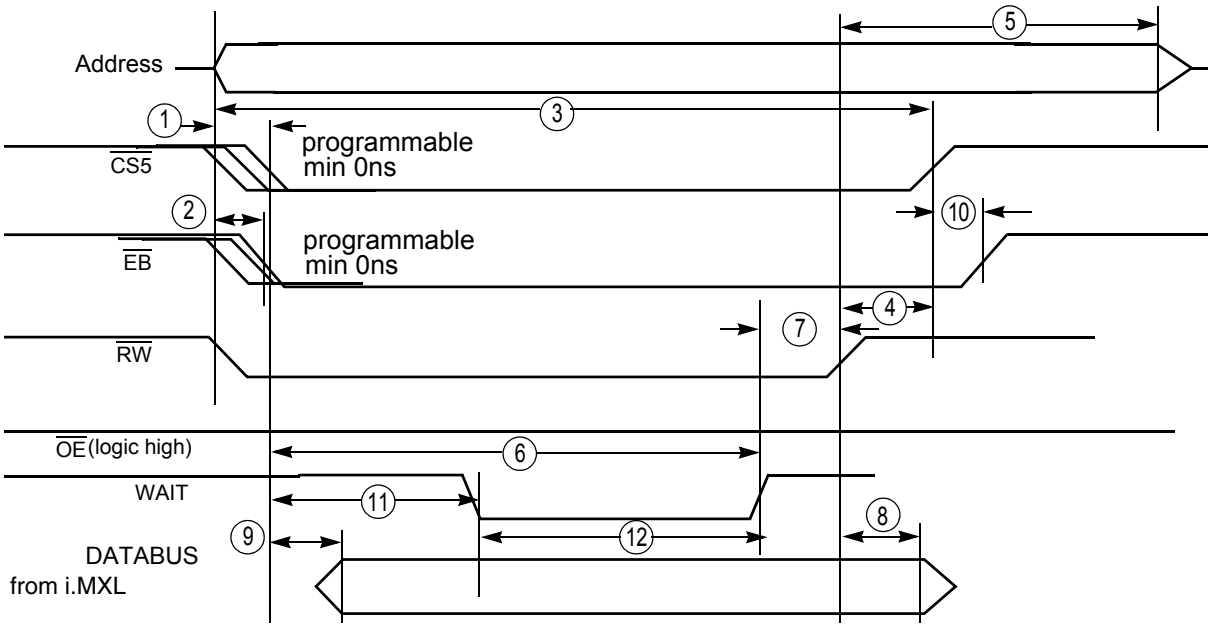


Figure 8. WAIT Write Cycle without DMA

Table 15. WAIT Write Cycle without DMA: WSC = 111111, DTACK_SEL=1, HCLK=96MHz

Number	Characteristic	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	$\overline{CS5}$ assertion time	See note 2	–	ns
2	$\overline{EB}$ assertion time	See note 2	–	ns
3	$\overline{CS5}$ pulse width	3T	–	ns
4	$\overline{RW}$ negated before $\overline{CS5}$ is negated	2.5T-3.63	2.5T-1.16	ns
5	$\overline{RW}$ negated to Address inactive	64.22	–	ns
6	Wait asserted after $\overline{CS5}$ asserted	–	1020T	ns

Table 16. WAIT Write Cycle DMA Enabled: WSC = 111111, DTACK_SEL=1, HCLK=96MHz

Number	Characteristic	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	$\overline{CS5}$ assertion time	See note 2	–	ns
2	$\overline{EB}$ assertion time	See note 2	–	ns
3	$\overline{CS5}$ pulse width	3T	–	ns
4	$\overline{RW}$ negated before $\overline{CS5}$ is negated	2.5T-3.63	2.5T-1.16	ns
5	Address inactived after $\overline{CS}$ negated	–	0.09	ns
6	Wait asserted after $\overline{CS5}$ asserted	–	1020T	ns
7	Wait asserted to $\overline{RW}$ negated	T+2.66	2T+7.96	ns
8	Data hold timing after $\overline{RW}$ negated	2T+0.03	–	ns
9	Data ready after $\overline{CS5}$ is asserted	–	T	ns
10	$\overline{CS}$ deactive to next $\overline{CS}$ active	T	–	ns
11	$\overline{EB}$ negate after $\overline{CS}$ negate	0.5T	0.5T+0.5	
12	Wait becomes low after $\overline{CS5}$ asserted	0	1019T	ns
13	Wait pulse width	1T	1020T	ns

Note:
1. T is the system clock period. (For 96 MHz system clock, T=10.42 ns)
2. $\overline{CS5}$ assertion can be controlled by CSA bits. $\overline{EB}$ assertion also can be programmable by WEA bits in CS5L register.
3. Address becomes valid and $\overline{RW}$ asserts at the start of write access cycle.
4.The external wait input requirement is eliminated when $\overline{CS5}$ is programmed to use internal wait state.

4.4.3 EIM External Bus Timing

The External Interface Module (EIM) is the interface to devices external to the i.MXL, including generation of chip-selects for external peripherals and memory. The timing diagram for the EIM is shown in Figure 5, and Table 12 defines the parameters of signals.

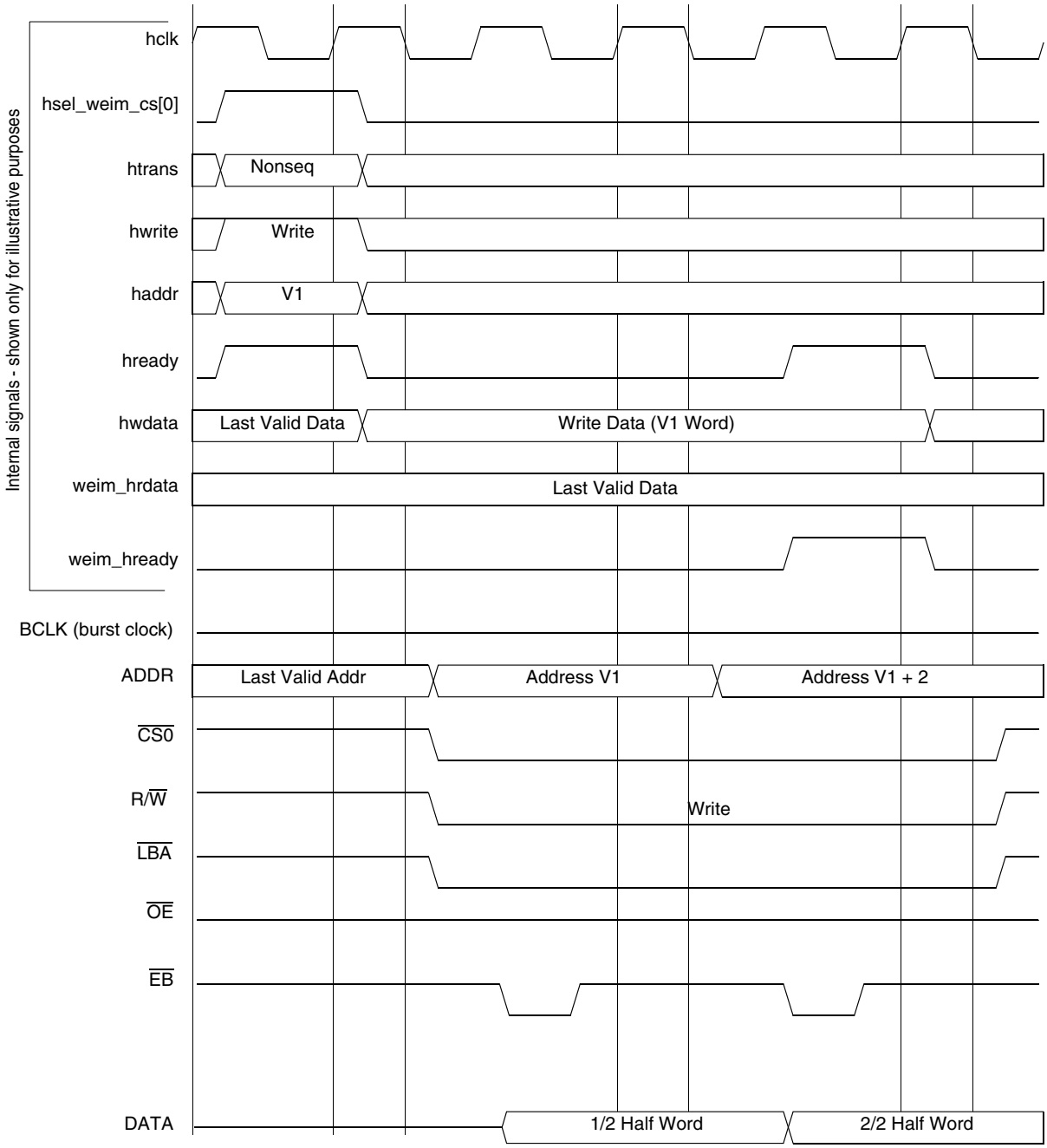
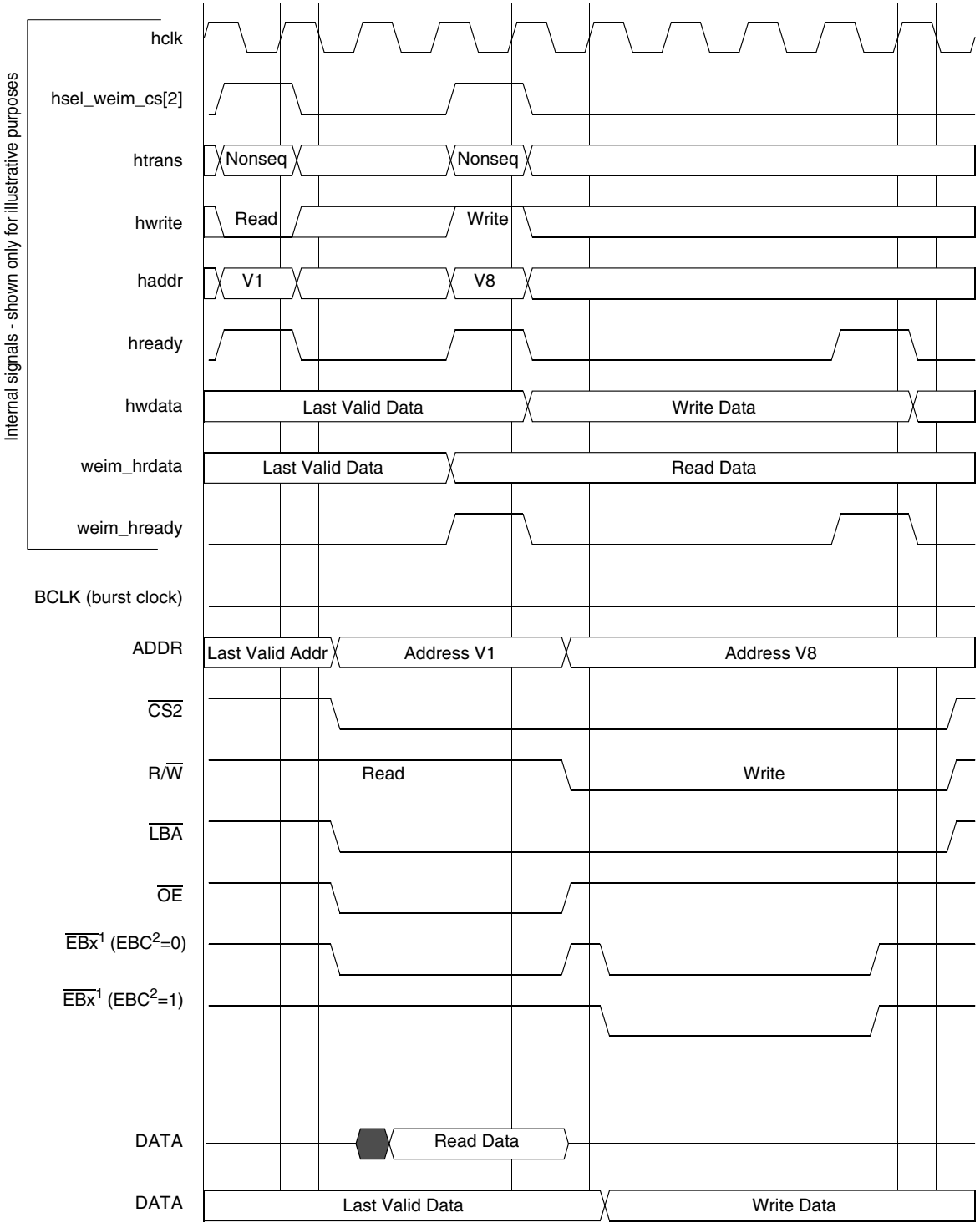
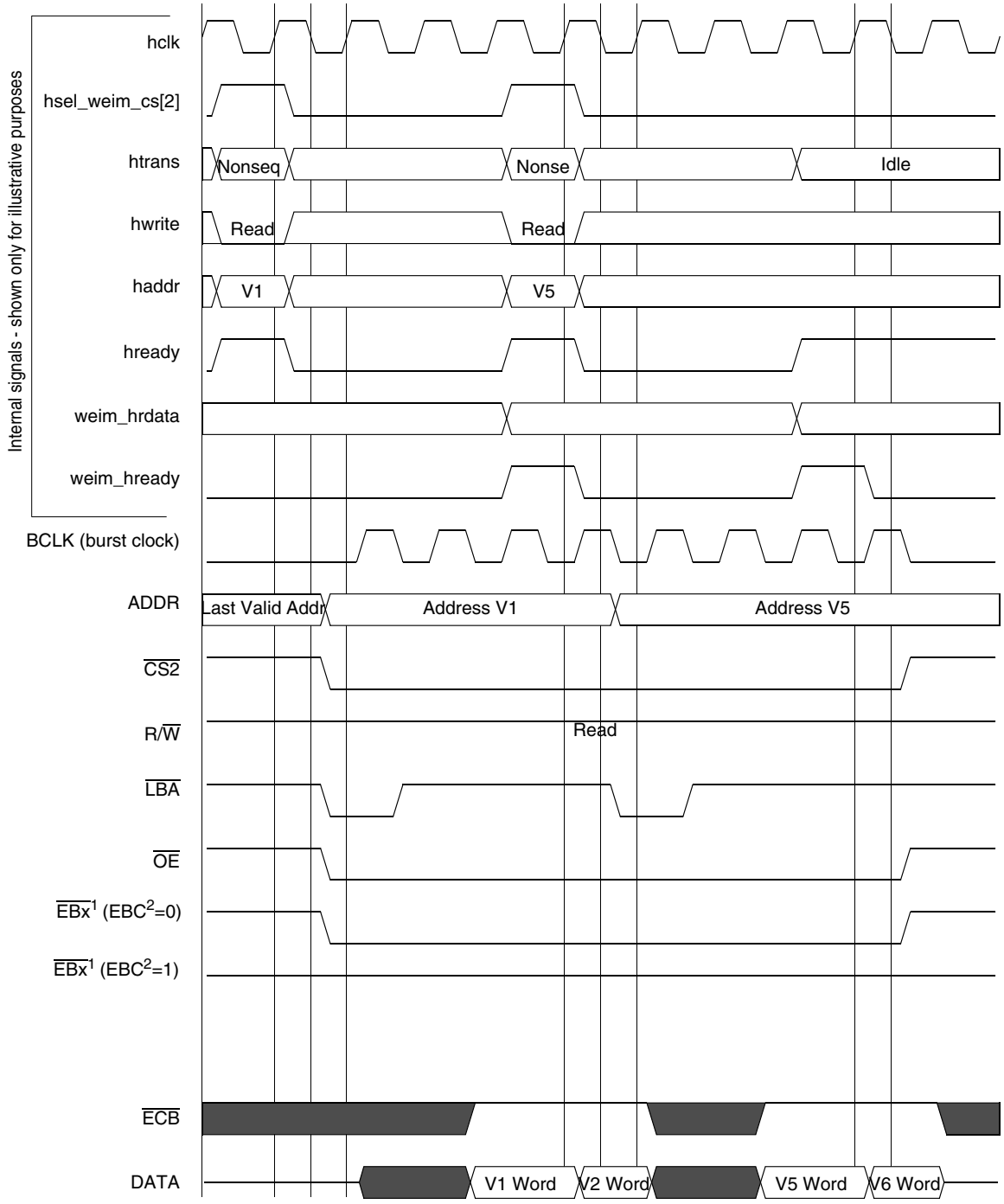


Figure 13. WSC = 1, WEA = 1, WEN = 2, A.WORD/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 22. WSC = 2, WWS = 2, WEA = 1, WEN = 2, A.HALF/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 28. WSC = 3, SYNC = 1, A.HALF/E.HALF

4.4.4 Non-TFT Panel Timing

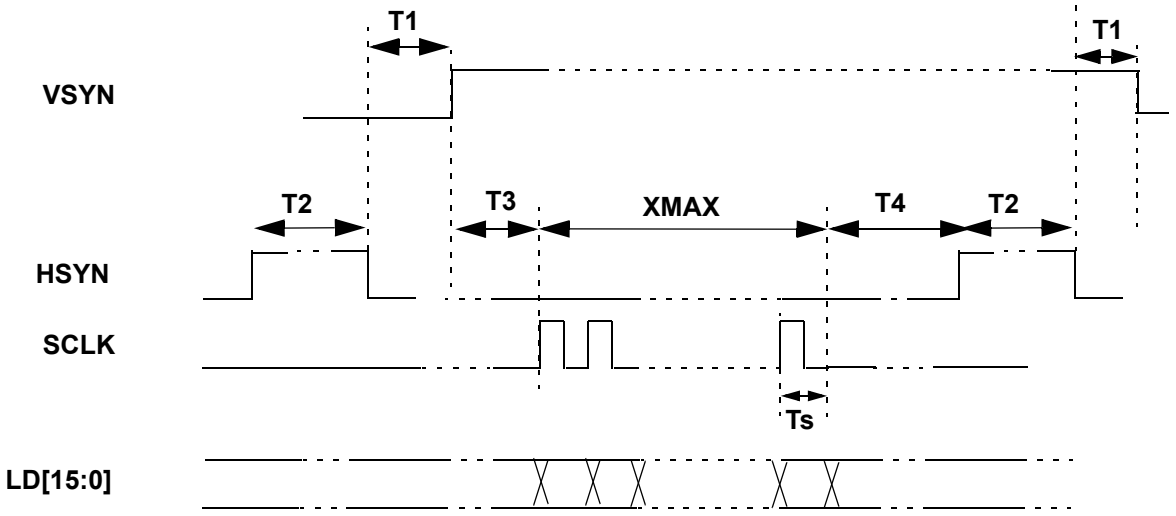


Figure 33. Non-TFT Panel Timing

Table 17. Non TFT Panel Timing Diagram

Symbol	Parameter	Allowed Register Minimum Value[1, 2]	Actual Value	Unit
T1	HSYN to VSYN delay[3]	0	HWAIT2+2	Tpix[4]
T2	HSYN pulse width	0	HWIDTH+1	Tpix
T3	VSYN to SCLK	–	0 ≤ T3 ≤ Ts[5]	–
T4	SCLK to HSYN	0	HWAIT1+1	Tpix

1 Maximum frequency of LCDC_CLK is 48 MHz, which is controlled by Peripheral Clock Divider Register.

2 Maximum frequency of SCLK is HCLK / 5, otherwise LD output will be wrong.

3 VSYN, HSYN and SCLK can be programmed as active high or active low. In the above timing diagram, all these 3 signals are active high.

4 Tpix is the pixel clock period which equals LCDC_CLK period * (PCD + 1).

5 Ts is the shift clock period. Ts = Tpix * (panel data bus width).

4.5 SPI Timing Diagrams

To use the internal transmit (TX) and receive (RX) data FIFOs when the SPI 1 module is configured as a master, two control signals are used for data transfer rate control: the $\overline{SS}$ signal (output) and the $\overline{SPI\_RDY}$ signal (input). The SPI1 Sample Period Control Register (PERIODREG1) and the SPI2 Sample Period Control Register (PERIODREG2) can also be programmed to a fixed data transfer rate for either SPI 1 or SPI 2. When the SPI 1 module is configured as a slave, the user can configure the SPI1 Control Register (CONTROLREG1) to match the external SPI master's timing. In this configuration, $\overline{SS}$ becomes an input signal, and is used to latch data into or load data out to the internal data shift registers, as well as to increment the data FIFO. Figure 34 through Figure 38 show the timing relationship of the master SPI using different triggering mechanisms.

Table 18. Timing Parameter Table for Figure 34 through Figure 38

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	$\overline{\text{SPI\_RDY}}$ to $\overline{\text{SS}}$ output low	2T[1]	–	ns
2	$\overline{\text{SS}}$ output low to first SCLK edge	3 • Tsclk[2]	–	ns
3	Last SCLK edge to $\overline{\text{SS}}$ output high	2 • Tsclk	–	ns
4	$\overline{\text{SS}}$ output high to $\overline{\text{SPI\_RDY}}$ low	0	–	ns
5	$\overline{\text{SS}}$ output pulse width	Tsclk + WAIT [3]	–	ns
6	$\overline{\text{SS}}$ input low to first SCLK edge	T	–	ns
7	$\overline{\text{SS}}$ input pulse width	T	–	ns

1 T = CSPI system clock period (PERCLK2).

2 Tsclk = Period of SCLK.

3 WAIT = Number of bit clocks (SCLK) or 32.768 kHz clocks per Sample Period Control Register.

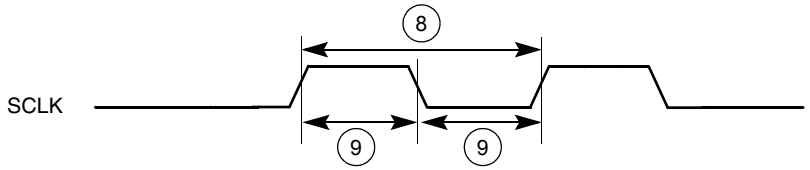


Figure 39. SPI SCLK Timing Diagram

Table 19. Timing Parameter Table for SPI SCLK

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
8	SCLK frequency	0	10	MHz
9	SCLK pulse width	100	–	ns

4.6 LCD Controller

This section includes timing diagrams for the LCD controller. For detailed timing diagrams of the LCD controller with various display configurations, refer to the LCD controller chapter of the *MC9328MXL Reference Manual*.

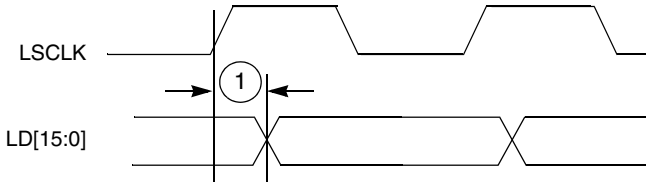


Figure 40. SCLK to LD Timing Diagram

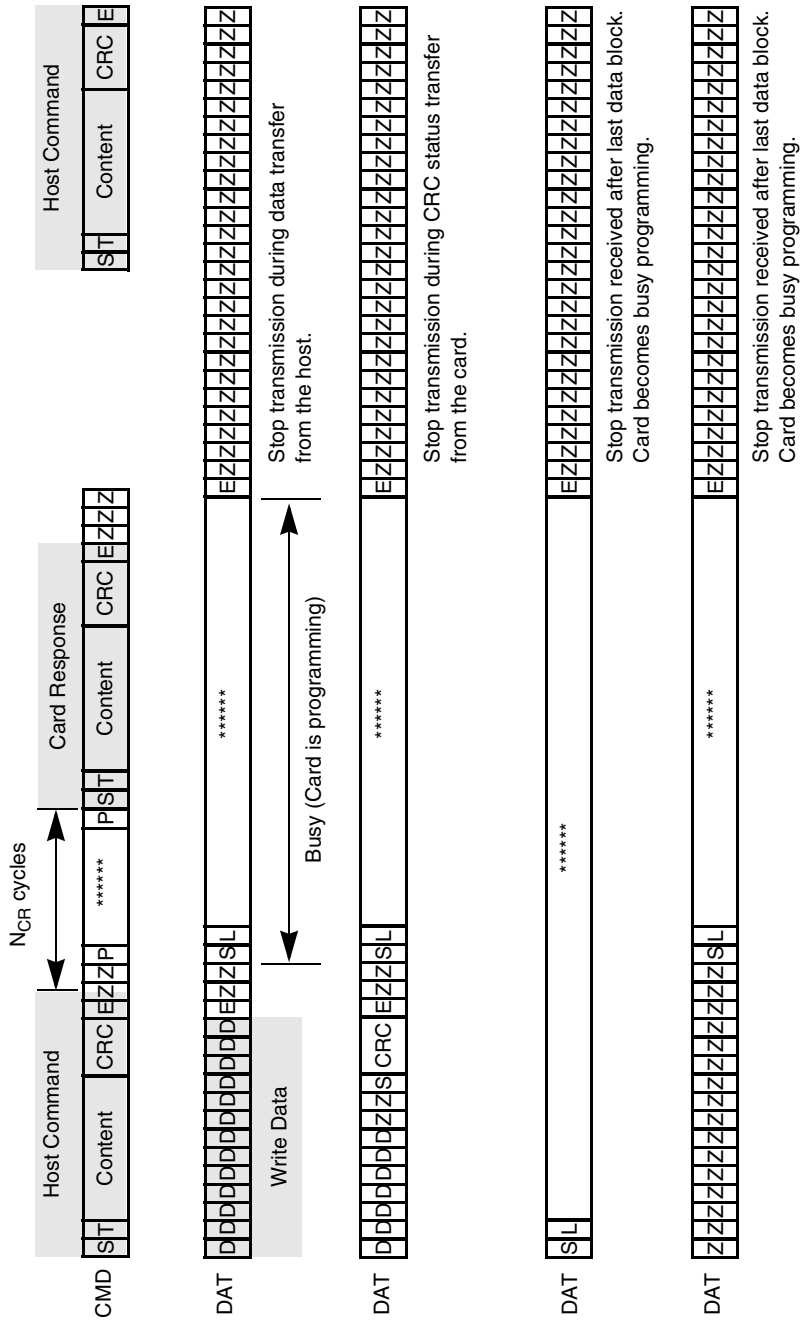


Figure 47. Stop Transmission During Different Scenarios

Table 24. Timing Values for Figure 43 through Figure 47

Parameter	Symbol	Minimum	Maximum	Unit
MMC/SD bus clock, CLK (All values are referred to minimum (VIH) and maximum (VIL)				
Command response cycle	NCR	2	64	Clock cycles
Identification response cycle	NID	5	5	Clock cycles
Access time delay cycle	NAC	2	TAAC + NSAC	Clock cycles

Table 24. Timing Values for Figure 43 through Figure 47 (Continued)

Parameter	Symbol	Minimum	Maximum	Unit
Command read cycle	NRC	8	–	Clock cycles
Command-command cycle	NCC	8	–	Clock cycles
Command write cycle	NWR	2	–	Clock cycles
Stop transmission cycle	NST	2	2	Clock cycles
TAAC: Data read access time -1 defined in CSD register bit[119:112] NSAC: Data read access time -2 in CLK cycles (NSAC·100) defined in CSD register bit[111:104]				

4.7.2 SDIO-IRQ and ReadWait Service Handling

In SDIO, there is a 1-bit or 4-bit interrupt response from the SDIO peripheral card. In 1-bit mode, the interrupt response is simply that the SD_DAT[1] line is held low. The SD_DAT[1] line is not used as data in this mode. The memory controller generates an interrupt according to this low and the system interrupt continues until the source is removed (SD_DAT[1] returns to its high level).

In 4-bit mode, the interrupt is less simple. The interrupt triggers at a particular period called the “Interrupt Period” during the data access, and the controller must sample SD_DAT[1] during this short period to determine the IRQ status of the attached card. The interrupt period only happens at the boundary of each block (512 bytes).

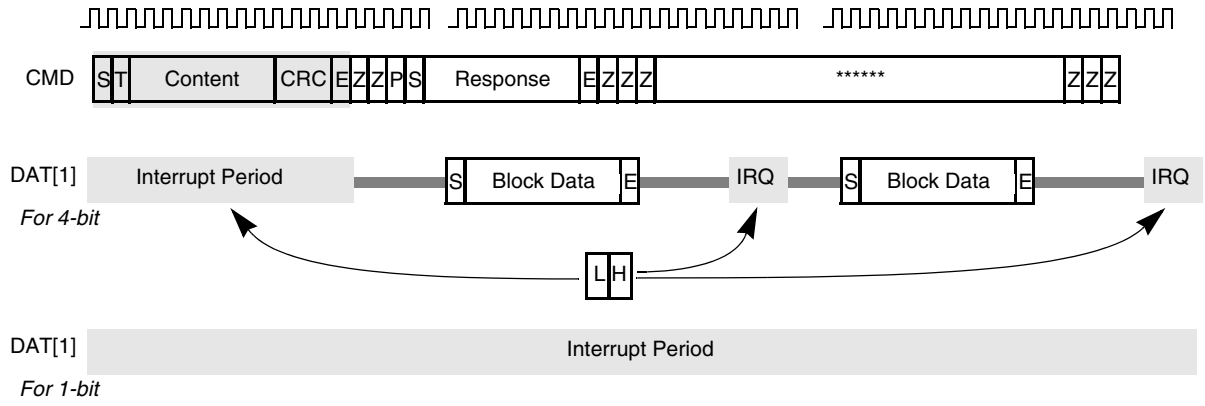


Figure 48. SDIO IRQ Timing Diagram

ReadWait is another feature in SDIO that allows the user to submit commands during the data transfer. In this mode, the block temporarily pauses the data transfer operation counter and related status, yet keeps the clock running, and allows the user to submit commands as normal. After all commands are submitted, the user can switch back to the data transfer operation and all counter and status values are resumed as access continues.

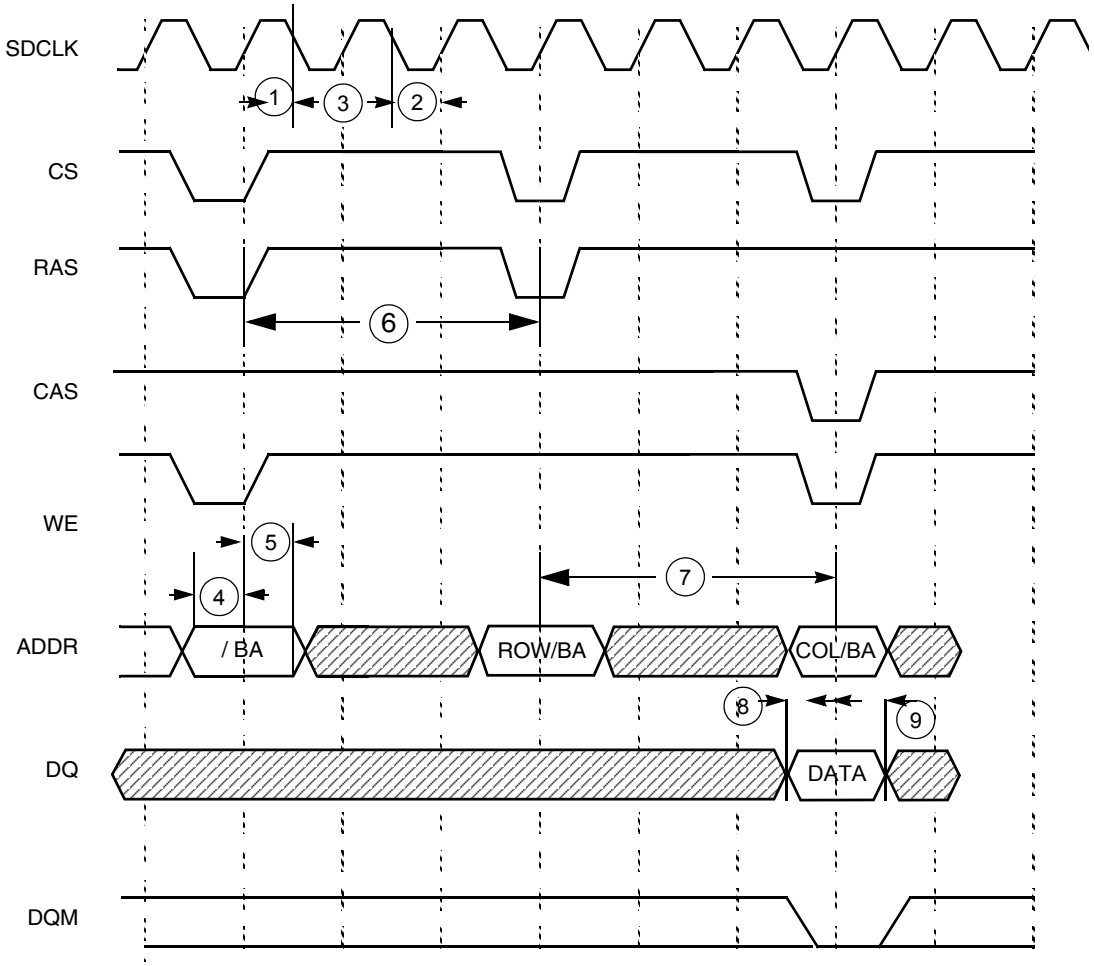


Figure 53. SDRAM Write Cycle Timing Diagram

Table 28. SDRAM Write Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
1	SDRAM clock high-level width	2.67	–	4	–	ns
2	SDRAM clock low-level width	6	–	4	–	ns
3	SDRAM clock cycle time	11.4	–	10	–	ns
4	Address setup time	3.42	–	3	–	ns
5	Address hold time	2.28	–	2	–	ns
6	Precharge cycle period[1]	t_{RP}[2]	–	t_{RP2}	–	ns
7	Active to read/write command delay	t_{RCD2}	–	t_{RCD2}	–	ns
8	Data setup time	4.0	–	2	–	ns
9	Data hold time	2.28	–	2	–	ns

1 Precharge cycle timing is included in the write timing diagram.

2 t_{RP} and t_{RCD} = SDRAM clock cycle time. These settings can be found in the *MC9328MXL reference manual*.

5 Pin-Out and Package Information

Table 37 illustrates the package pin assignments for the 256-pin MAPBGA package. For a complete listing of signals, see the Signal Multiplexing Table 3 on page 9.

Table 37. i.MXL 256 MAPBGA Pin Assignments

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
A	NVSS	SD_DAT3	SD_CLK	NVSS	USBD_ AFE	NVDD4	NVSS	UART1_ RTS	UART1_ RXD	NVDD3	N.C.	N.C.	QVDD4	N.C.	N.C.	N.C.	A
B	A24	SD_DAT1	SD_CMD	PB16	USBD_ ROE	USBD_VP	SSI_ RXCLK	SSI_ TXCLK	SPI1_ SCLK	N.C.	N.C.	N.C.	QVSS	N.C.	N.C.	N.C.	B
C	A23	D31	SD_DAT0	PB15	USBD_ RCV	UART2_ CTS	UART2_ RXD	SSI_ RXFS	UART1_ TXD	N.C.	N.C.	N.C.	N.C.	N.C.	N.C.	N.C.	C
D	A22	D30	D29	PB14	USBD_ SUSPND	USBD_ VPO	USBD_ VMO	SSI_ RXDAT	SPI1_ SPI_RDY	N.C.	N.C.	N.C.	N.C.	N.C.	N.C.	N.C.	D
E	A20	A21	D28	D26	SD_DAT2	USBD_VM	UART2_ RTS	SSI_ TXDAT	SPI1_SS	N.C.	N.C.	N.C.	N.C.	N.C.	N.C.	N.C.	E
F	A18	D27	D25	A19	A16	PB18	UART2_ TXD	SSI_ TXFS	SPI1_ MISO	N.C.	N.C.	REV	N.C.	N.C.	LSCLK	SPL_SPR	F
G	A15	A17	D24	D23	D21	PB17	PB19	UART1_ CTS	SPI1_ MOSI	N.C.	CLS	CONTRAST	ACD/OE	LP/ HSYNC	FLM/ VSYNC	LD1	G
H	A13	D22	A14	D20	NVDD1	NVDD1	NVSS	QVSS	QVDD1	PS	LD0	LD2	LD4	LD5	LD9	LD3	H
J	A12	A11	D18	D19	NVDD1	NVDD1	NVSS	NVDD1	NVSS	NVSS	LD6	LD7	LD8	LD11	QVDD3	QVSS	J
K	A10	D16	A9	D17	NVDD1	NVSS	NVSS	NVDD1	NVDD2	NVDD2	LD10	LD12	LD13	LD14	TMR2OUT	LD15	K
L	A8	A7	D13	D15	D14	NVDD1	NVSS	CAS	TCK	TIN	PWMO	CSI_MCLK	CSI_D0	CSI_D1	CSI_D2	CSI_D3	L
M	A5	D12	D11	A6	SDCLK	NVSS	RW	MA10	RAS	RESET_IN	BIG_ ENDIAN	CSI_D4	CSI_ HSYNC	CSI_VSYNC	CSI_D6	CSI_D5	M
N	A4	EB1	D10	D7	A0	D4	PA17	D1	DQM1	RESET_SF[1]	RESET_ OUT	BOOT2	CSI_ PIXCLK	CSI_D7	TMS	TDI	N
P	A3	D9	EB0	CS3	D6	ECB	D2	D3	DQM3	SDCKE1	BOOT3	BOOT0	TRST	I2C_SCL	I2C_SDA	XTAL32K	P
R	EB2	EB3	A1	CS4	D8	D5	LBA	BCLK[2]	D0	DQM0	SDCKE0	POR	BOOT1	TDO	QVDD2	EXTAL32K	R
T	NVSS	A2	OE	CS5	CS2	CS1	CS0	MA11	DQM2	SDWE	CLKO	AVDD1	TRISTATE	EXTAL16M	XTAL16M	QVSS	T
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	

1 This signal is not used and should be floated in an actual application.

2 burst clock